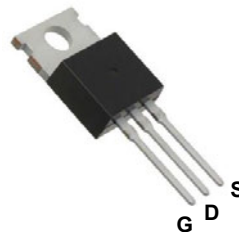
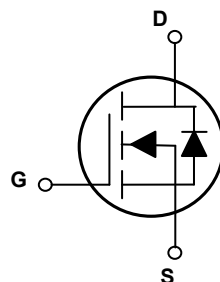


### Main Product Characteristics

$V_{(BR)DSS}$	100V
$R_{DS(ON)}$	4.4mΩ (max.)
$I_D$	180A



TO-220



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFH10120 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous, at Steady-State, ( $T_C=25^{\circ}\text{C}$ ) <sup>1</sup>	$I_D$	180	A
Drain Current-Continuous, at Steady-State, ( $T_C=100^{\circ}\text{C}$ ) <sup>1</sup>		130	
Drain Current-Pulsed <sup>2</sup>	$I_{DM}$	720	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	780	mJ
Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	$P_D$	208	W
Linear Derating Factor ( $T_C=25^{\circ}\text{C}$ )		1.7	$^{\circ}\text{C}/\text{W}$
Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.6	$^{\circ}\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^{\circ}\text{C}$

### Electrical Characteristics ( $T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=125^{\circ}\text{C}$	-	-	50	
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=20V$	-	-	100	nA
		$V_{DS}=0V, V_{GS}=-20V$	-	-	-100	
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=50A$	-	3.6	4.4	m $\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.2	3	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS}=50V, I_D=20A, V_{GS}=10V$	-	152	-	nC
Gate-Source Charge	$Q_{gs}$		-	45.5	-	
Gate-Drain ("Miller") Charge	$Q_{gd}$		-	45.2	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=50V, R_{GEN}=3\Omega, V_{GS}=10V, R_L=1\Omega$	-	40	-	nS
Rise Time	$t_r$		-	66	-	
Turn-Off Delay Time	$t_{d(off)}$		-	101	-	
Fall Time	$t_f$		-	41	-	
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V, F=1\text{MHz}$	-	8402	-	pF
Output Capacitance	$C_{oss}$		-	890	-	
Reverse Transfer Capacitance	$C_{rss}$		-	34	-	
Gate Resistance	$R_g$	$F=1\text{MHz}$	-	1.8	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	180	A
Pulsed Source Current (Body Diode)	$I_{SM}$		-	-	720	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=50A$	-	1	1.2	V
Reverse Recovery Time	$t_{rr}$	$T_J=25^{\circ}\text{C}, I_F=50A, di/dt=100A/\mu s$	-	82	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	0.24	-	uc

Note:

1. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating: Pulsed width limited by maximum junction temperature.
3.  $L=0.5\text{mH}$ ,  $V_{DD}=80V$ ,  $T_J=25^{\circ}\text{C}$ .
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## Typical Electrical and Thermal Characteristic Curves

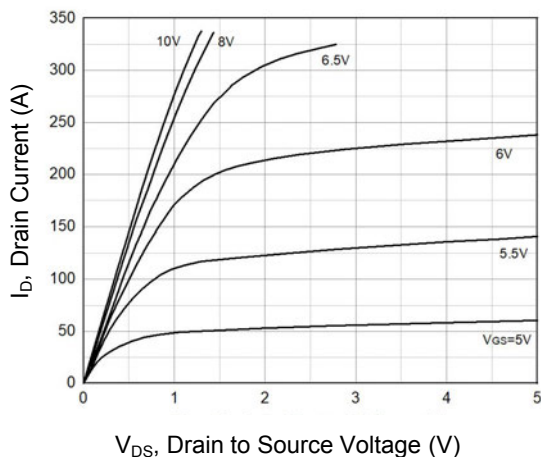


Figure 1. Typical Output Characteristics

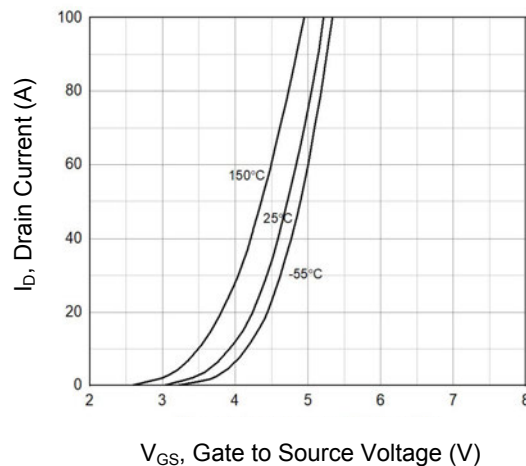


Figure 2. Typical Transfer Characteristics

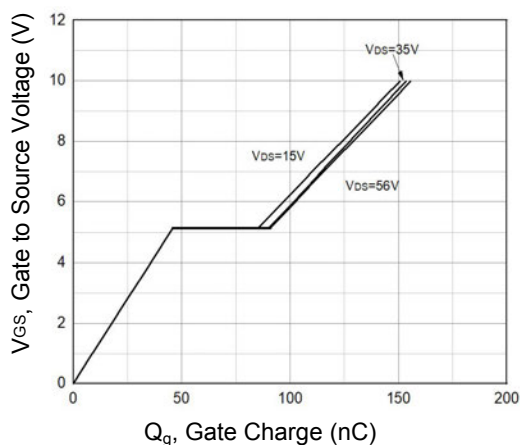


Figure 3. Gate Charge Characteristics

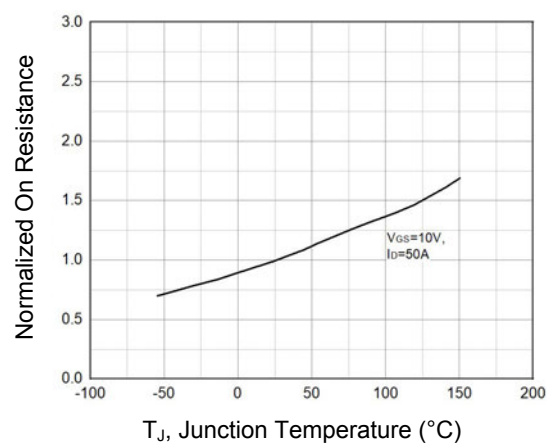


Figure 4. Normalized On-Resistance vs. Junction Temperature

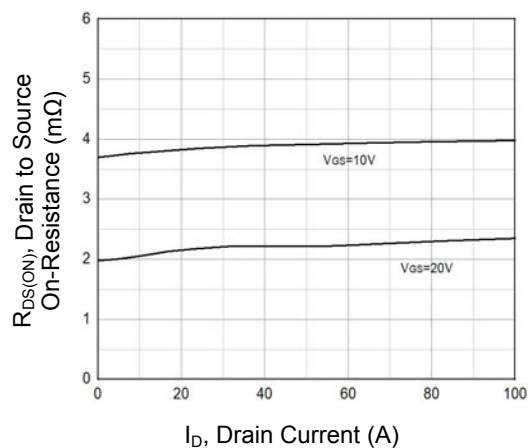


Figure 5. On Resistance vs. Drain Current

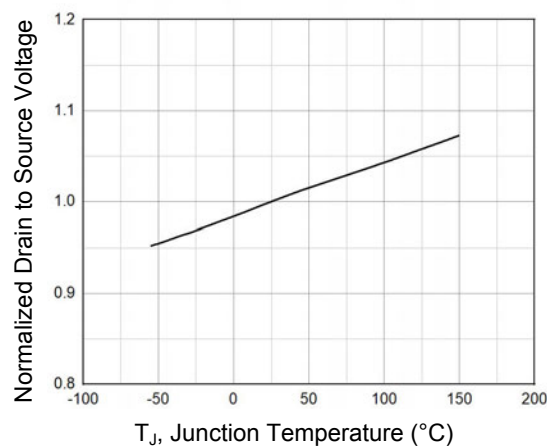
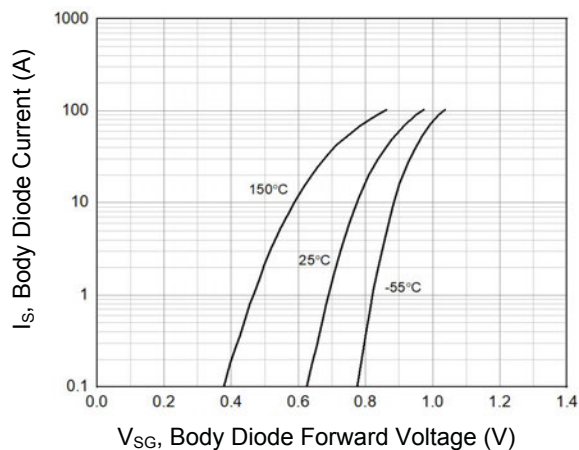
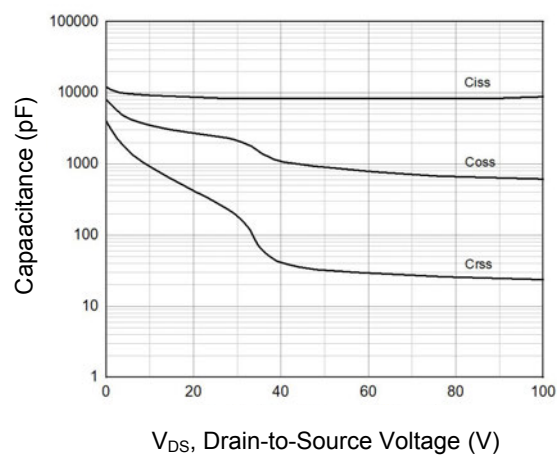


Figure 6. Normalized  $BV_{DSS}$  vs. Junction Temperature

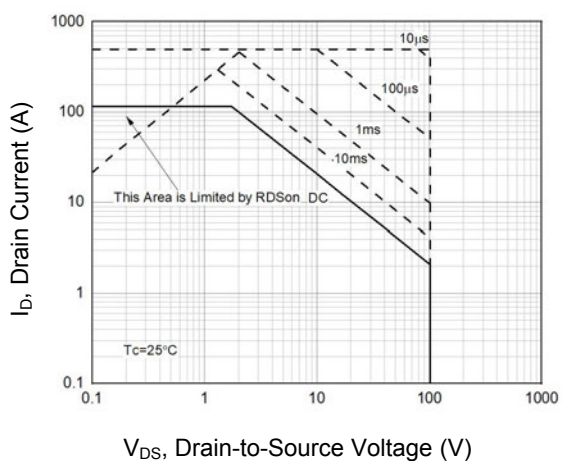
### Typical Electrical and Thermal Characteristic Curves



**Figure 7. Body Diode Characteristics**

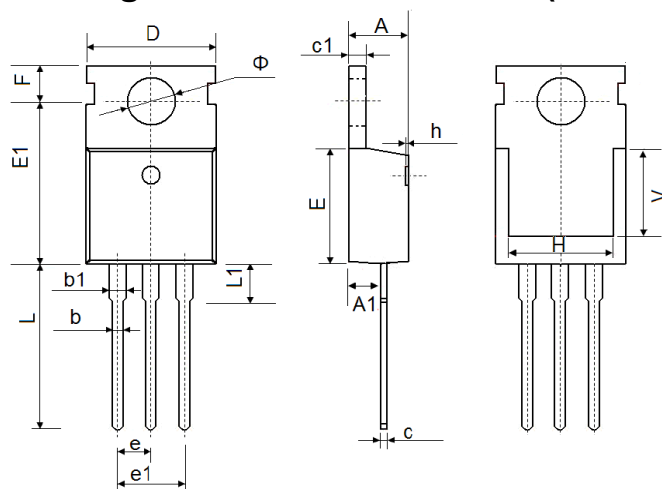


**Figure 8. Capacitance Characteristics**



**Figure 9. Safe Operation Area**

## Package Outline Dimensions (TO-220)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150

## Order Information

Device	Package	Marking	Quantity	HSF Status
GSFH10120	TO-220	H4R410	50pcs / Tube	RoHS Compliant